



**MEC8-RA, MEC8-EM SERIES**

**(0,80 mm) .0315"**

# RIGHT ANGLE/EDGE MOUNT SOCKETS

**Mates with:**  
(1,60 mm) .062" thick cards

**SPECIFICATIONS**

For complete specifications and recommended PCB layouts see [www.samtec.com?MEC8-RA](http://www.samtec.com?MEC8-RA)

**Insulator Material:** Black LCP  
**Contact Material:** Phosphor Bronze  
**Plating:** Au or Sn over 50µ" (1,27 µm) Ni  
**Operating Temp Range:** -55°C to +125°C  
**Insertion Depth:** (3,94 mm) .155" to (6,25 mm) .246"  
**Current Rating:** 2.0 A per pin (6 adjacent pins powered)  
**Voltage Rating:** 265 VAC  
**RoHS Compliant:** Yes  
**Lead-Free Solderable:** Yes

**RECOGNITIONS**

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)

**MEC8** - **1** POSITIONS PER ROW - **02** PLATING OPTION - **D** - **RA1** - OTHER OPTION

**10, 13, 20, 25, 30, 37, 40, 49, 50**

**-L**  
= 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

**-TR**  
= Tape & Reel Packaging

MEC8-RA	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	8.5 GHz / 17 Gbps
Differential Pair Signaling	9.5 GHz / 19 Gbps

\*Test board losses de-embedded from performance data.  
Complete test data available at [www.samtec.com?MEC8-RA](http://www.samtec.com?MEC8-RA) or contact [sig@samtec.com](mailto:sig@samtec.com)

**ALSO AVAILABLE (MOQ Required)**

- 1 mm mating card thickness option
- Latching option

Contact Samtec.

**Mates with:**  
(1,60 mm) .062" thick cards

**SPECIFICATIONS**

For complete specifications and recommended PCB layouts see [www.samtec.com?MEC8-EM](http://www.samtec.com?MEC8-EM)

**Insulator Material:** Black LCP  
**Contact Material:** Phosphor Bronze  
**Plating:** Au or Sn over 50µ" (1,27 µm) Ni  
**Operating Temp Range:** -55°C to +125°C  
**Insertion Depth:** (4,32 mm) .170" to (5,66 mm) .223"  
**Current Rating:** 1.8 A per pin (6 adjacent pins powered)  
**Voltage Rating:** 265 VAC  
**RoHS Compliant:** Yes  
**Lead-Free Solderable:** Yes

**RECOGNITIONS**

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)

**Note:** Some sizes, styles and options are non-standard, non-returnable.

**MEC8** - **1** POSITIONS PER ROW - **02** PLATING OPTION - **D** - **-EM2**

**10, 20, 30, 40, 50, 60, 70**

**-L**  
= 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

**-EM2**  
= (1,60 mm) .062" thick PCB

MEC8-EM	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	9.5 GHz / 18 Gbps
Differential Pair Signaling	9 GHz / 18 Gbps

\*Test board losses de-embedded from performance data.  
Complete test data available at [www.samtec.com?MEC8-EM](http://www.samtec.com?MEC8-EM) or contact [sig@samtec.com](mailto:sig@samtec.com)

POSITIONS PER ROW	A	B
40	(18,90) .744	(36,60) 1.441
50	(22,90) .902	(44,60) 1.756
60	(26,90) 1.059	(52,60) 2.071
70	(30,90) 1.217	(60,60) 2.386

**ALSO AVAILABLE (MOQ Required)**

- 1 mm mating card thickness option

Contact Samtec.

Due to technical progress, all designs, specifications and components are subject to change without notice.